

# Product / Process Change Notification



N° 2016-031-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

## Implementation of 200mm wafer diameter for 4<sup>th</sup> generation emitter controlled diode bare die products

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **16. August 2016**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates:  
“**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG  
Chairman of the Supervisory Board: Wolfgang Mayrhofer  
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Arunjai Mittal  
Registered Office: Neubiberg  
Commercial Register: München HRB 126492

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- **Products affected:** Emitter controlled diode technology products, 4<sup>th</sup> generation as listed per sales code and SP number (ordering code) in attachment 1\_cip16031-a.

► **Detailed Change Information:**

**Subject:** Implementation of 200mm wafer diameter

**Reason:** To ensure continuous deliveries to our customers, the fabrication for above products requires a capacity extension.

**Description of Change:**

	<u>Old</u>	<u>New</u>
<ul style="list-style-type: none"> <li>Wafer diameter</li> </ul>	<ul style="list-style-type: none"> <li>150 mm on respective 6" sawing frame and packing</li> </ul>	<ul style="list-style-type: none"> <li>150 mm on respective 6" sawing frame and packing</li> <li>and</li> <li>200 mm on respective 8" sawing frame and packing</li> </ul>
<ul style="list-style-type: none"> <li>Backside metallization technique</li> </ul>	<ul style="list-style-type: none"> <li>150 mm production: Evaporation</li> </ul>	<ul style="list-style-type: none"> <li>200 mm production: Sputtering</li> </ul>
<ul style="list-style-type: none"> <li>UV sawing foil</li> </ul>	<ul style="list-style-type: none"> <li>Adwill D-175</li> </ul>	<ul style="list-style-type: none"> <li>Adwill D-175 for 150 mm wafer diameter</li> <li>and</li> <li>Adwill D-495H for 200 mm wafer diameter</li> </ul>
<ul style="list-style-type: none"> <li>Sales code and SP number (ordering code)</li> </ul>	<ul style="list-style-type: none"> <li>Depends on product. Details see attachment 1_cip16031_a.</li> </ul>	
<ul style="list-style-type: none"> <li>Lot number</li> </ul>	<ul style="list-style-type: none"> <li>VCxxxxxx = 150mm production</li> </ul>	<ul style="list-style-type: none"> <li>VCxxxxxx = 150mm production</li> <li>and</li> <li>VExxxxxx = 200mm production</li> </ul>

- **Product Identification:** Internal traceability assured via basic type, lot number and development code.
- External traceability by Sales code, SP number and Barcode Product Label.

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## ► Impact of Change:

- No impact on parameters and reliability as proven via product and technology qualification. Processes are optimized to meet identical product performance according to already applied Infineon specifications.
- Extended production capacity.
- No change in chip orientation.
- No change in packing materials besides size.
- New datasheets are available in Infineon Internet or at your local sales office.

## ► Attachments:

1\_cip16031\_a Affected product list including list of changes in sales name and ordering code

## ► Time Schedule:

- Final qualification report:
- First samples available:
- Intended start of delivery:

Available on request.

All types on request with a lead time of 8 weeks from customer sample order till PCN sample delivery.

01-December-2016, or earlier on customer request.